SN74LV4052A-Q1 Automotive Dual 4-Channel Analog Multiplexers and Demultiplexers

1 Features

- Qualified for automotive applications
- AEC-Q100 qualified with the following results:
  - Device temperature grade 1: –40°C to +125°C ambient operating temperature range
  - Device HBM ESD classification level 2
  - Device CDM ESD classification level C4B
- Supports mixed-mode voltage operation on all ports
- Fast switching
- High on-off output-voltage ratio
- Low crosstalk between switches
- Extremely low input current

2 Applications

- Automotive:
  - Signal gating
  - Chopping
  - Modulation or demodulation (modem)
  - Signal multiplexing for analog-to-digital and digital-to-analog conversion systems

3 Description

These dual 4-channel CMOS analog multiplexers and demultiplexers are designed for 1.0V to 5.5V V_{CC} operation.

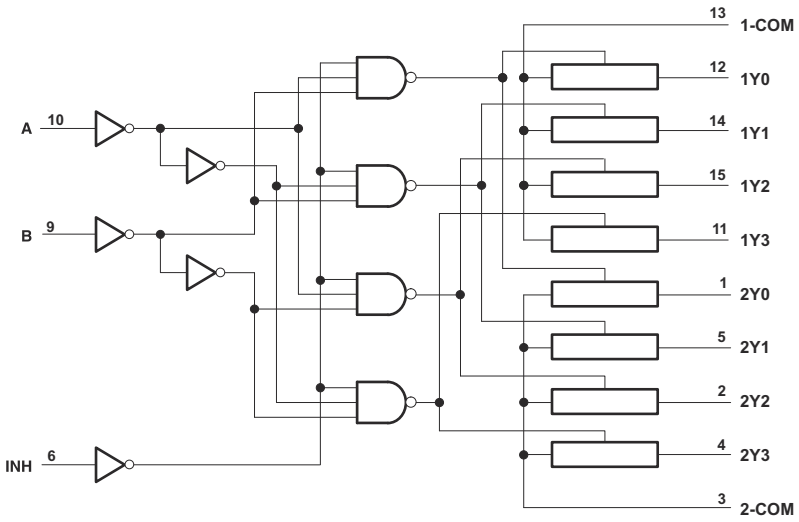
The SN7LV4052A-Q1 devices handle both analog and digital signals. Each channel permits signals with amplitudes up to 5.5V (peak).

Applications include signal gating, chopping, modulation or demodulation (modem), and signal multiplexing for analog-to-digital and digital-to-analog conversion systems.

Package Information

PART NUMBER	PACKAGE(1)	PACKAGE SIZE(2)
SN74LV4052A-Q1	PW (TSSOP, 16)	5mm × 6.4mm

(1) For more information, see Section 11.
(2) The package size (length × width) is a nominal value and includes pins, where applicable.



Logic Diagram (Positive Logic)

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4 Pin Configuration and Functions

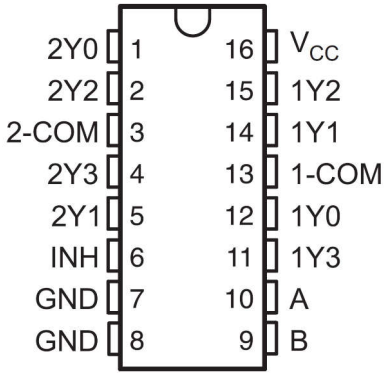


Figure 4-1. PW Package, 16-Pin TSSOP (Top View)

Table 4-1. Pin Functions

PIN		TYPE(1) (2)	DESCRIPTION
NAME	NO.		
2Y0	1	I(1)	Input to mux 2
2Y2	2	I(1)	Input to mux 2
2-COM	3	O(1)	Output of mux 2
2Y3	4	I(1)	Input to mux 2
2Y1	5	I(1)	Input to mux 2
INH	6	I	Enables the outputs of the device. Logic low level with turn the outputs on, high level will turn them off.
GND	7	-	Ground
GND	8	-	Ground
B	9	I	Selector line for outputs (see Section 7.4 for specific information)
A	10	I	Selector line for outputs (see Section 7.4 for specific information)
1Y3	11	I(1)	Input to mux 1
1Y0	12	I(1)	Input to mux 1
1-COM	13	O(1)	Output of mux 1
1Y1	14	I(1)	Input to mux 1
1Y2	15	I(1)	Input to mux 1
V_{CC}	16	I	Device power input

(1) These I/O descriptions represent the device when used as a multiplexer, when this device is operated as a demultiplexer pins 1Y0, 1Y1, 1Y2, 1Y3, 2Y0, 2Y1, 2Y2, 2Y3 may be considered outputs (O) and pins 1-COM and 2-COM may be considered inputs (I).
(2) I = input, O = output

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1) (3)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		–0.5	7.0	V
V_I	Logic input voltage range		–0.5	7.0	V
V_{IO}	Switch I/O voltage range(2) (3)		–0.5	V_{CC} + 0.5	V
I_{IK}	Input clamp current	V_I < 0	–20		mA
I_{IOK}	Switch IO diode clamp current	V_{IO} < 0 or V_{IO} > V_{CC}	–50		mA
I_T	Switch continuous current	V_{IO} = 0 to V_{CC}		±25	mA
	Continuous current through V_{CC} or GND			±50	mA
T_{stg}	Storage temperature		–65	150	°C

(1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. Absolute maximum ratings do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If briefly operating outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not sustain damage, but it may not be fully functional. Operating the device in this manner may affect device reliability, functionality, performance, and shorten the device lifetime.
(2) Pins are diode-clamped to the power-supply rails. Over voltage signals must be voltage and current limited to maximum ratings.
(3) This value is limited to 5.5V maximum

5.2 ESD Ratings

				VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per AEC Q100-002(1)	All pins	±2000	V
$V_{(ESD)}$	Electrostatic discharge	Charged device model (CDM), per AEC Q100-011	All pins	±500	V

(1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

5.3 Thermal Information: SN74LV4052A-Q1

THERMAL METRIC (1)		TMUX4052A-Q1 PW (TSSOP) 16 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	140.2	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	72.6	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	98.7	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	13.4	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	97.3	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

5.4 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		1(2)		5.5	V
V_{IH}	High-level input voltage, logic control inputs	V_{CC} = 1.65	1.2		5.5	V
		V_{CC} = 2V	1.5		5.5	
		V_{CC} = 2.3V to 2.7V	V_{CC} x 0.7		5.5	
		V_{CC} = 3V to 3.6V	V_{CC} x 0.7		5.5	
		V_{CC} = 4.5V to 5.5V	V_{CC} x 0.7		5.5	
V_{IL}	Low-level input voltage, logic control inputs	V_{CC} = 1.65V to 2.7V	0		0.4	V
		V_{CC} = 1.65V to 2.7V	0		0.5	
		V_{CC} = 1.65V to 2.7V	0		V_{CC} x 0.3	
		V_{CC} = 3V to 3.6V	0		V_{CC} x 0.3	
		V_{CC} = 4.5V to 5.5V	0		V_{CC} x 0.3	
V_I	Logic control input voltage		0		5.5	V
V_{IO}	Switch input or output voltage		0		V_{CC}	V
Δt/ΔV	Logic input transition rise or fall rate	V_{CC} = 1.0V to 2.0V			500	ns/V
		V_{CC} = 2.0V to 2.7V			200	
		V_{CC} = 3V to 3.6V			100	
		V_{CC} = 4.5V to 5.5V			20	
T_A	Ambient temperature		–40		125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND for proper device operation. Refer to TI application report *Implications of Slow or Floating CMOS Inputs*, SCBA004.
(2) When using a V_{CC} of ≤1.2 V, it is recommended to use these devices only for transmitting digital signals. When supply voltage is near 1.2 V the analog switch ON resistance becomes very non-linear

5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		Condition	T_A	V_{CC}	MIN	TYP	MAX	UNIT
r_{ON}	ON-state switch resistance	I_T = 2mA, V_I = V_{CC} or GND, V_{INH} = V_{IL}	25°C	1.65V		60	150	Ω
			–40°C to 85°C				225	
			–40°C to 125°C				225	
			25°C	2.3V		38	180	
			–40°C to 85°C				225	
			–40°C to 125°C				225	
			25°C	3V		30	150	
			–40°C to 85°C				190	
			–40°C to 125°C				190	
			25°C	4.5V		22	75	
			–40°C to 85°C				100	
			–40°C to 125°C				100	

5.5 Electrical Characteristics (continued)

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		Condition	T_A	V_{CC}	MIN	TYP	MAX	UNIT
$r_{ON(p)}$	Peak ON-state resistance	I_T = 2mA, V_I = GND to V_{CC}, V_{INH} = V_{IL}	25°C	1.65V		220	600	Ω
			–40°C to 85°C				700	
			–40°C to 125°C				700	
			25°C	2.3V		113	500	
			–40°C to 85°C				600	
			–40°C to 125°C				600	
			25°C	3V		54	180	
			–40°C to 85°C				225	
			–40°C to 125°C				225	
			25°C	4.5V		31	100	
			–40°C to 85°C				125	
			–40°C to 125°C				125	
Δr_{ON}	Difference in ON-state resistance between switches	I_T = 2mA, V_I = GND to V_{CC}, V_{INH} = V_{IL}	25°C	1.65V				Ω
			–40°C to 85°C					
			–40°C to 85°C					
			–40°C to 85°C	2.3V		2.1	30	
			–40°C to 85°C				40	
			–40°C to 125°C				40	
			25°C	3V		1.4	20	
			–40°C to 85°C				30	
			–40°C to 125°C				30	
			25°C	4.5V		1.3	15	
			–40°C to 85°C				20	
			–40°C to 125°C				20	
I_{IH} I_{IL}	Control input current	V_I = 5.5V or GND	25°C	0 to 5.5V	-0.1		0.1	µA
			–40°C to 85°C		-1		1	
			–40°C to 125°C		-2		2	
$I_{S(off)}$	OFF-state switch leakage current	V_I = V_{CC} and V_O = GND, or V_I = GND and V_O = V_{CC}, V_{INH} = V_{IH}	25°C	5.5V	-0.1		0.1	µA
			–40°C to 85°C		-1		1	
			–40°C to 125°C		-2		2	
$I_{S(on)}$	ON-state switch leakage current	V_I = V_{CC} or GND, V_{INH} = V_{IL}	25°C	5.5V	-0.1		0.1	µA
			–40°C to 85°C		-1		1	
			–40°C to 125°C		-2		2	
I_{CC}	Supply current	V_I = V_{CC} or GND V_{INH} = 0V	25°C	5.5V				µA
			–40°C to 85°C				20	
			–40°C to 125°C				40	
C_{IC}	Control input capacitance	f = 10MHz	25°C	3.3V		2		pF
C_{IS}	Common terminal capacitance 4052	f = 10MHz	25°C	3.3V				pF
C_{OS}	Switch terminal capacitance	f = 10MHz	25°C	3.3V		5.7		pF
C_F	Feedthrough capacitance	f = 10MHz	25°C	3.3V		0.5		pF

5.5 Electrical Characteristics (continued)

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		Condition	T_A	V_{CC}	MIN	TYP	MAX	UNIT
C_{PD}	Power dissipation capacitance 4052	C_L = 50pF, f = 10MHz	25°C	3.3V		11.8		pF

5.6 Timing Characteristics V_{CC} = 2.5V ± 0.2V

PARAMETER		FROM (INPUT)	TO (OUTPUT)	CONDITIONS	T_A	MIN	TYP	MAX	UNIT
t_{PLH} t_{PHL}	Propagation delay time	COM or Yn	Yn or COM	C_L = 15pF	25°C		1.9	10	ns
					–40°C to 85°C			16	
					–40°C to 125°C			18	
t_{PZH} t_{PZL}	Enable delay time	INH	COM or Yn	C_L = 15pF	25°C		6.6	18	ns
					–40°C to 85°C			23	
					–40°C to 125°C			25	
t_{PHZ} t_{PLZ}	Disable delay time	INH	COM or Yn	C_L = 15pF	25°C		7.4	18	ns
					–40°C to 85°C			23	
					–40°C to 125°C			25	
t_{PLH} t_{PHL}	Propagation delay time	COM or Yn	Yn or COM	C_L = 50pF	25°C		3.8	12	ns
					–40°C to 85°C			18	
					–40°C to 125°C			20	
t_{PZH} t_{PZL}	Enable delay time	INH	COM or Yn	C_L = 50pF	25°C		7.8	28	ns
					–40°C to 85°C			35	
					–40°C to 125°C			35	
t_{PHZ} t_{PLZ}	Disable delay time	INH	COM or Yn	C_L = 50pF	25°C		11.5	28	ns
					–40°C to 85°C			35	
					–40°C to 125°C			35	

5.7 Timing Characteristics V_{CC} = 3.3V ± 0.3V

PARAMETER		FROM (INPUT)	TO (OUTPUT)	CONDITIONS	T_A	MIN	TYP	MAX	UNIT
t_{PLH} t_{PHL}	Propagation delay time	COM or Yn	Yn or COM	C_L = 50pF	25°C		2.5	9	ns
					–40°C to 85°C			12	
					–40°C to 125°C			14	
t_{PZH} t_{PZL}	Enable delay time	INH	COM or Yn	C_L = 50pF	25°C		5.5	20	ns
					–40°C to 85°C			25	
					–40°C to 125°C			25	
t_{PHZ} t_{PLZ}	Disable delay time	INH	COM or Yn	C_L = 50pF	25°C		8.8	20	ns
					–40°C to 85°C			25	
					–40°C to 125°C			25	

5.8 Timing Characteristics V_{CC} = 5V ± 0.5V

PARAMETER		FROM (INPUT)	TO (OUTPUT)	CONDITIONS	T_A	MIN	TYP	MAX	UNIT
t_{PLH} t_{PHL}	Propagation delay time	COM or Yn	Yn or COM	C_L = 50pF	25°C		1.5	6	ns
					–40°C to 85°C			8	
					–40°C to 125°C			10	

5.8 Timing Characteristics V_{CC} = 5V ± 0.5V (continued)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	CONDITIONS	T_A	MIN	TYP	MAX	UNIT
t_{PZH} t_{PZL}	Enable delay time	INH	COM or Yn	C_L = 50pF	25°C		4	14	ns
					–40°C to 85°C			18	
					–40°C to 125°C			18	
t_{PHZ} t_{PLZ}	Disable delay time	INH	COM or Yn	C_L = 50pF	25°C		6.2	14	ns
					–40°C to 85°C			18	
					–40°C to 125°C			18	

5.9 AC Characteristics

PARAMETER	FROM (INPUT)	TO (OUTPUT)	Device	CONDITIONS		MIN	TYP	MAX	UNIT
Frequency response (switch on)	COM or Yn	Yn or COM	SN74LV4052	C_L = 50pF, R_L = 600Ω, F_{in} = 1MHz (sine wave)	V_{CC} = 2.3V		30		MHz
					V_{CC} = 3V		35		
					V_{CC} = 4.5V		50		
Feedthrough attenuation (switch off)	COM or Yn	Yn or COM	ALL	C_L = 50pF, R_L = 600Ω, F_{in} = 1MHz (sine wave)	V_{CC} = 2.3V		–45		dB
					V_{CC} = 3V		–45		
					V_{CC} = 4.5V		–45		
Crosstalk (between any switches)	COM or Yn	Yn or COM	ALL	C_L = 50pF, R_L = 600Ω, F_{in} = 1MHz (sine wave)	V_{CC} = 2.3V		20		mV
					V_{CC} = 3V		35		
					V_{CC} = 4.5V		60		
Sine-wave distortion	COM or Yn	Yn or COM	ALL	C_L = 50pF, R_L = 10kΩ, F_{in} = 1kHz (sine wave)	V_I = 2V_{p-p} V_{CC} = 2.3V		0.1		%
					V_I = 2.5V_{p-p} V_{CC} = 3V		0.1		
					V_I = 4V_{p-p} V_{CC} = 4.5V		0.1		

6 Parameter Measurement Information

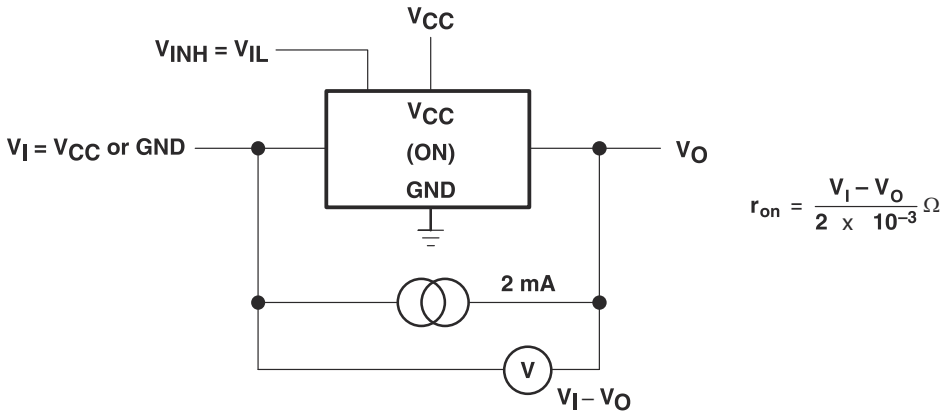


Figure 6-1. On-State Resistance Test Circuit

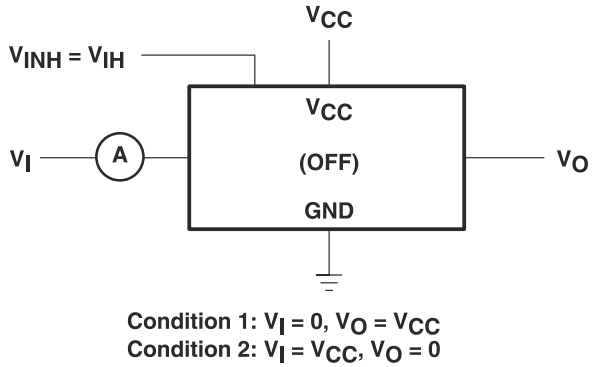


Figure 6-2. Off-State Switch Leakage-Current Test Circuit

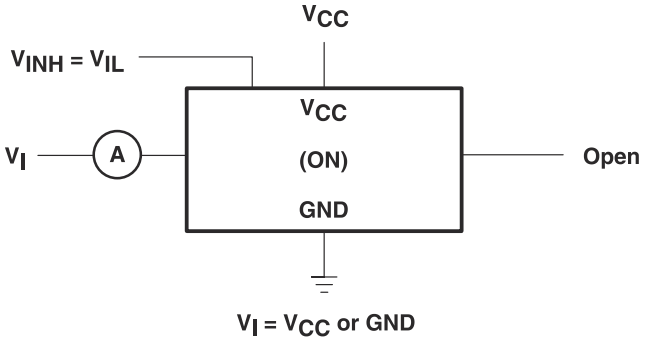


Figure 6-3. On-State Switch Leakage-Current Test Circuit

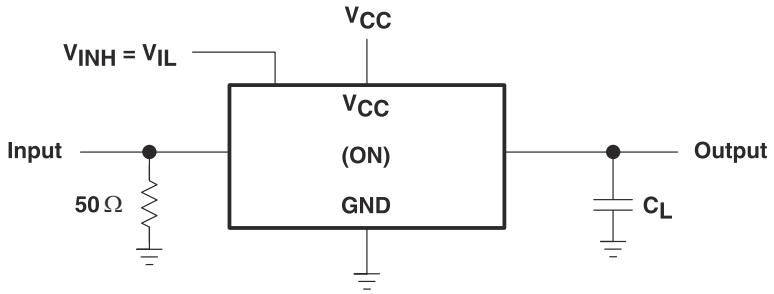
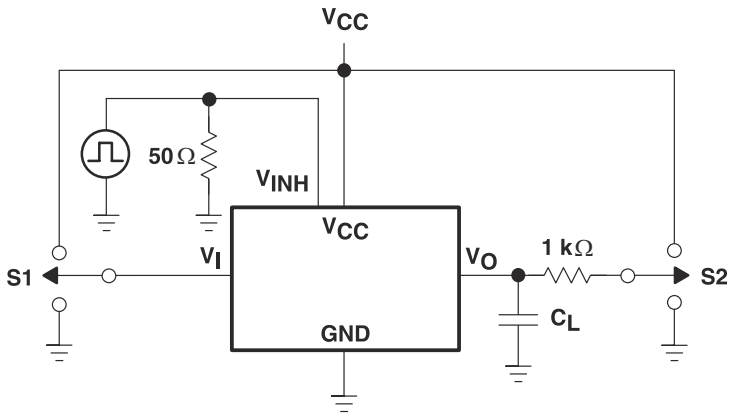
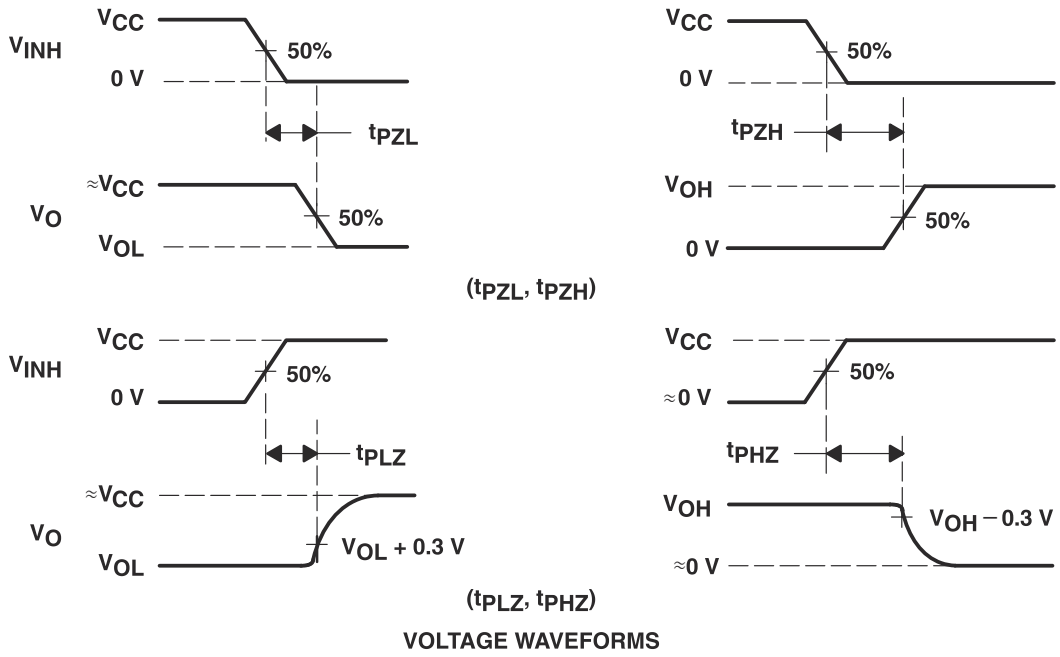


Figure 6-4. Propagation Delay Time, Signal Input to Signal Output



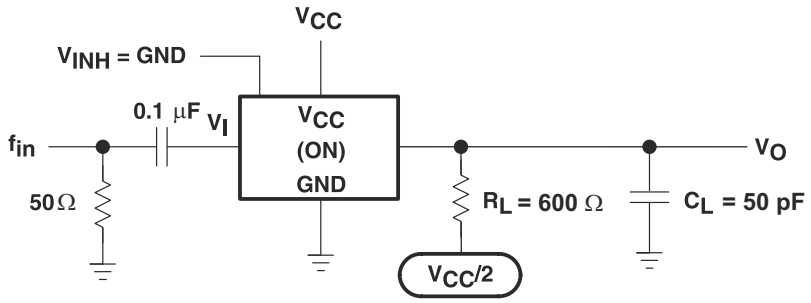
TEST	S1	S2
t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	GND V_{CC}	V_{CC} GND

TEST CIRCUIT



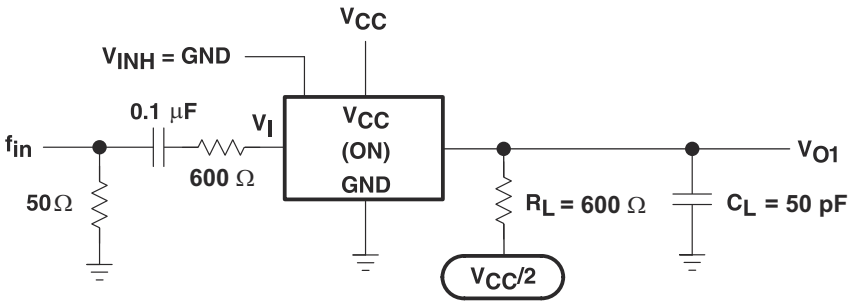
VOLTAGE WAVEFORMS

Figure 6-5. Switching Time (t_{PZL}, t_{PLZ}, t_{PZH}, t_{PHZ}), Control to Signal Output



NOTE A: f_{in} is a sine wave.

Figure 6-6. Frequency Response (Switch On)



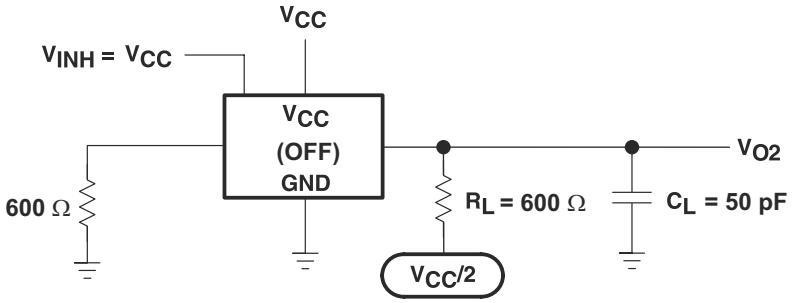


Figure 6-7. Crosstalk Between Any Two Switches

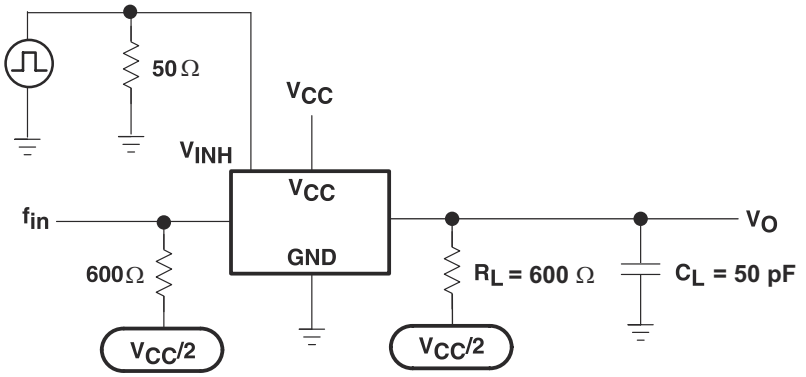


Figure 6-8. Crosstalk Between Control Input and Switch Output

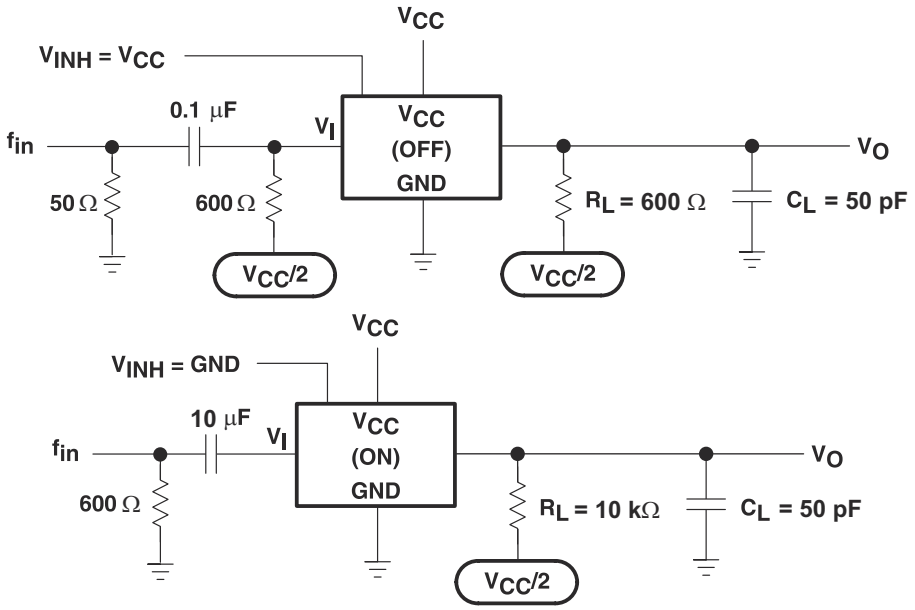


Figure 6-9. Feedthrough Attenuation (Switch Off)

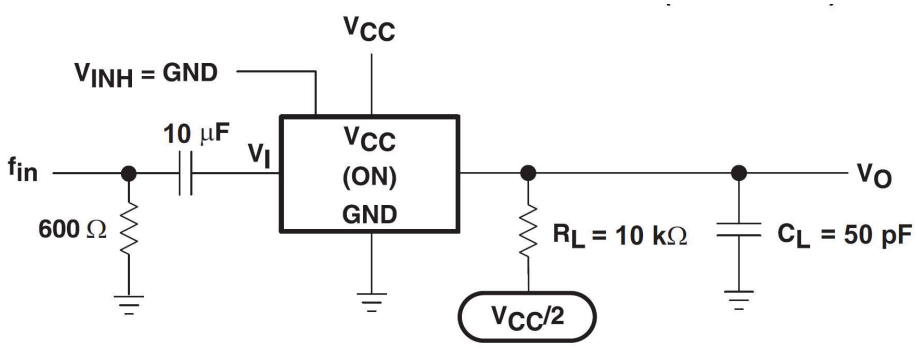


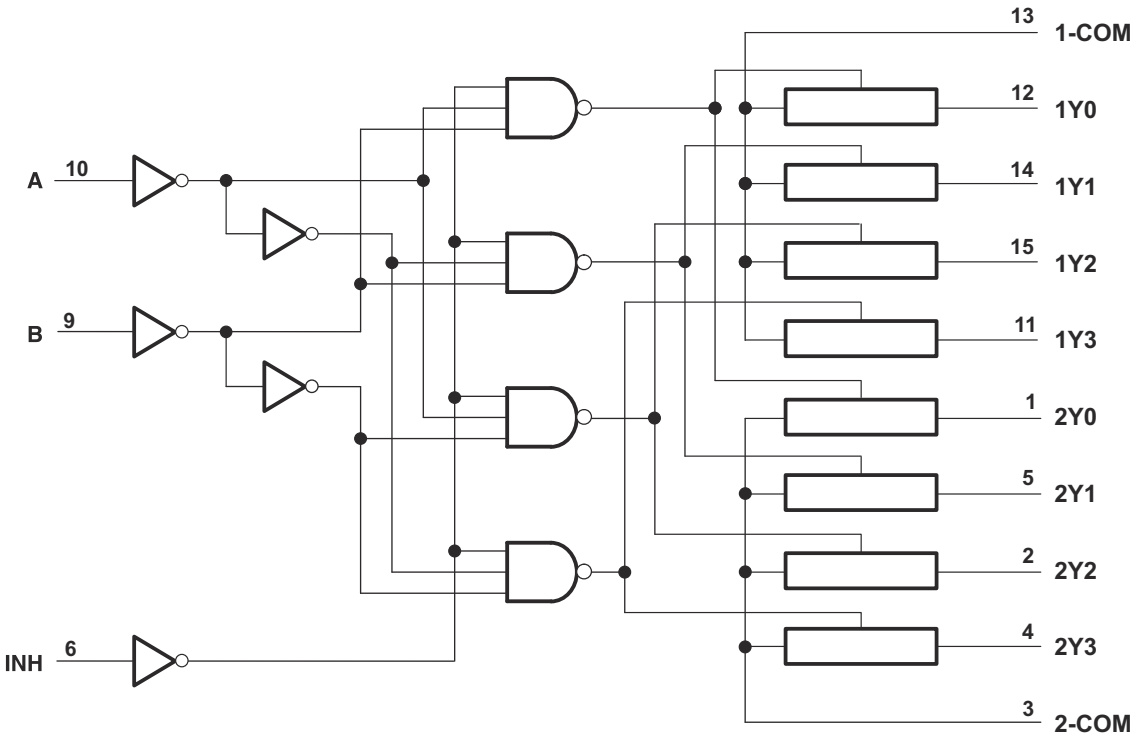
Figure 6-10. Sine-Wave Distortion

7 Detailed Description

7.1 Overview

This device is a dual 4-channel analog multiplexer. A multiplexer is often used when several signals need to share the same device or resource. This device allows the selection of one of these signals at a time for analysis or propagation.

7.2 Functional Block Diagram



7.3 Feature Description

This device contains 2 separate 4-channel multiplexers for use in a variety of applications. The 4-channel multiplexers can also be configured as demultiplexers by using the COM pins as inputs and the 1Yx or 2Yx pins as outputs. This device is qualified for automotive applications and has an extended temperature range of -40°C to 125°C (maximum depends on package type).

7.4 Device Functional Modes

Table 7-1. Function Table

INPUTS			ON CHANNEL
INH	B	A	
L	L	L	1Y0, 2Y0
L	L	H	1Y1, 2Y1
L	H	L	1Y2, 2Y2
L	H	H	1Y3, 2Y3
H	X	X	None

8 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

8.1 Application Information

A multiplexer is used in applications where multiple signals share a resource. In the following example, several different sensors are connected to the analog-to-digital converter (ADC) of a microcontroller (MCU).

8.2 Typical Application

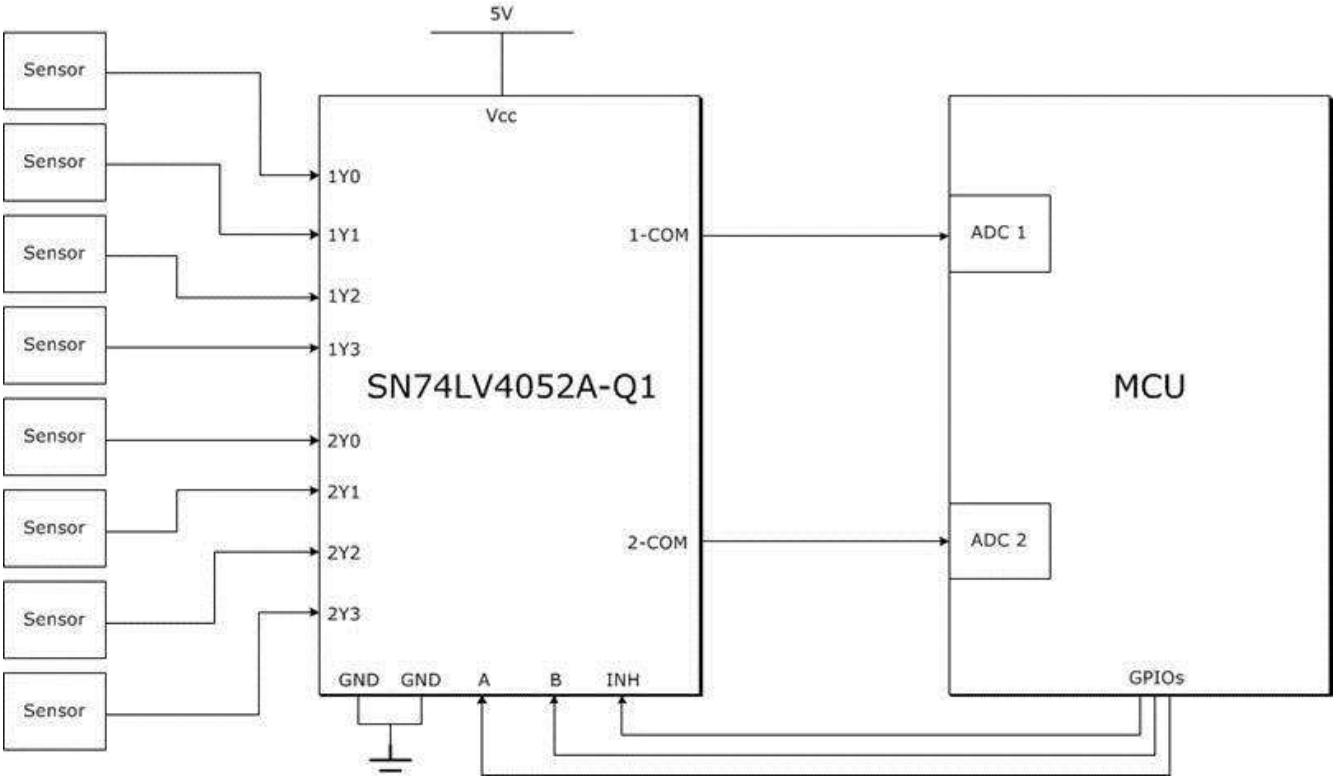


Figure 8-1. Typical Application Schematic

8.2.1 Design Requirements

Processing 8 different analog signals would normally require 8 separate ADCs, but the previous figure shows how to achieve this using only 2 ADCs and 3 GPIOs (general purpose input/outputs).

8.2.2 Detailed Design Procedure

To design with the SN74LV4052A-Q1, a stable input voltage between 2V (see *Recommended Operating Conditions* for details) and 5.5V must be available. The characteristics of the signal that is being multiplexed so that no important information is lost due to timing or voltage level incompatibility with this device is another important design consideration.

8.3 Power Supply Recommendations

Most systems have a common 3.3V or 5V rail that may be used to supply the V_{CC} pin of this device. If this is not available, then a Switch-Mode-Power-Supply (SMPS) or a Linear Dropout Regulator (LDO) may be used to supply this device from a higher voltage rail.

8.4 Layout

8.4.1 Layout Guidelines

In general, it is best to keep signal lines as short and as straight as possible. Incorporation of microstrip or stripline techniques is also recommended when signal lines are greater than 1 inch in length. These traces must be designed with a characteristic impedance of either 50Ω or 75Ω, as required by the application. Be careful placing this device too close to high voltage switching components, as they may cause interference.

8.4.2 Layout Example

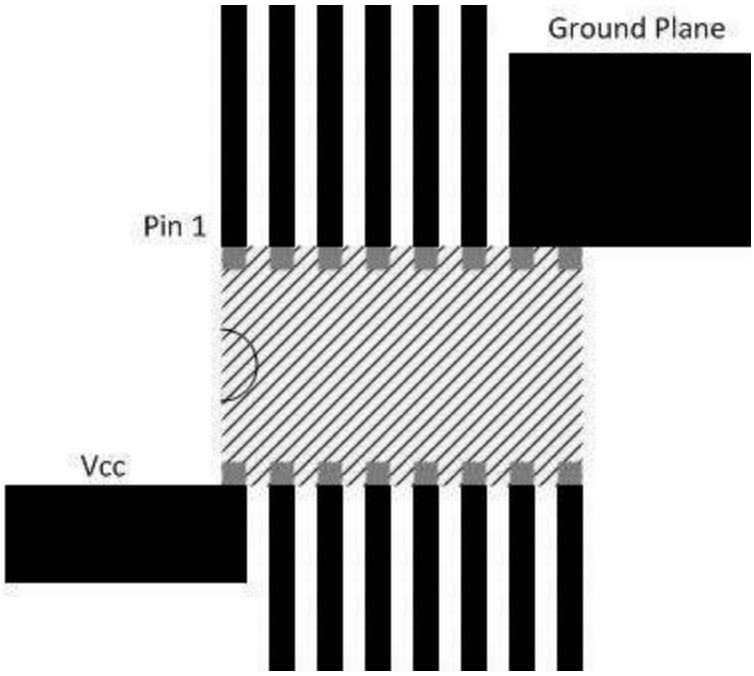


Figure 8-2. Layout Example Schematic

9 Device and Documentation Support

9.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

9.2 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

9.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.
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9.4 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

9.5 Glossary

TI Glossary	This glossary lists and explains terms, acronyms, and definitions.

10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision F (December 2014) to Revision G (June 2024)	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document	1
• Updated the *Package Information* table to include package leads	1
• Added new VIH and VIL Specifications at 1.65V Vcc	5

Changes from Revision E (November 2012) to Revision F (December 2014)	Page
• Added new VIH and VIL Specifications at 1.65V Vcc	5
• Added Ron, Ron Peak, and Delta Ron Specifications at 1.65V Vcc	5

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV4052AQPWRQ1	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	4052AQ1	Samples
SN74LV4052ATDRQ1	NRND	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	L4052AQ	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF SN74LV4052A-Q1 :

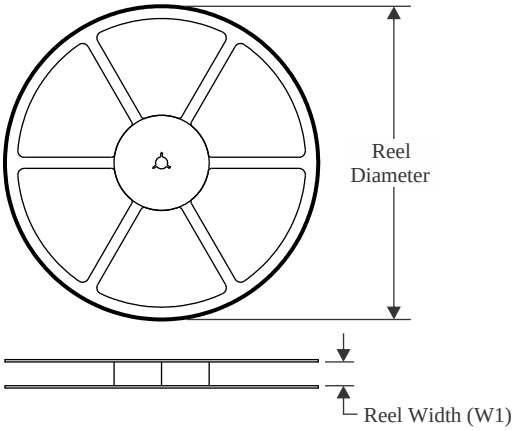
- Catalog : SN74LV4052A
- Enhanced Product : SN74LV4052A-EP

NOTE: Qualified Version Definitions:

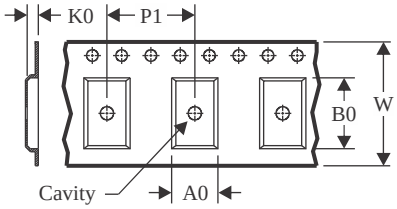
- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

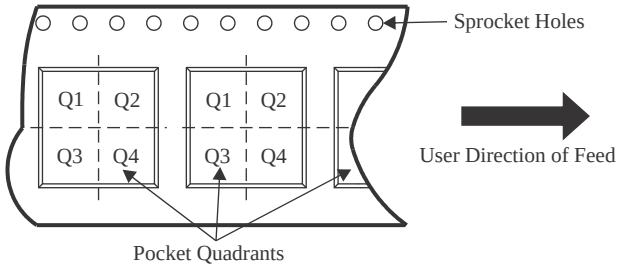


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

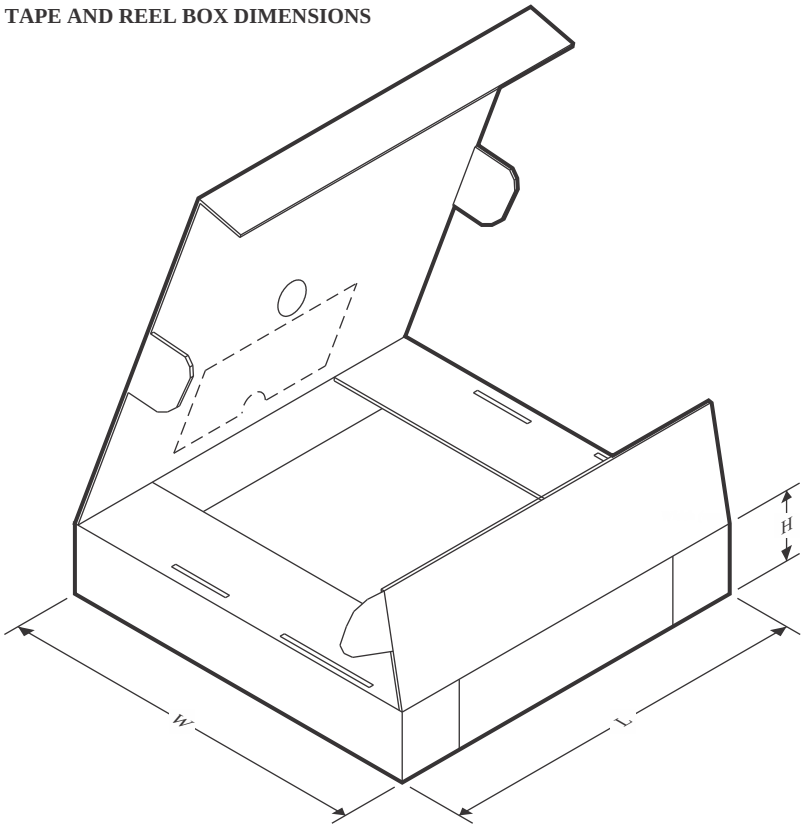
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CLV4052ATPWRG4Q1	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV4052AQPWRQ1	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV4052ATPWRQ1	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

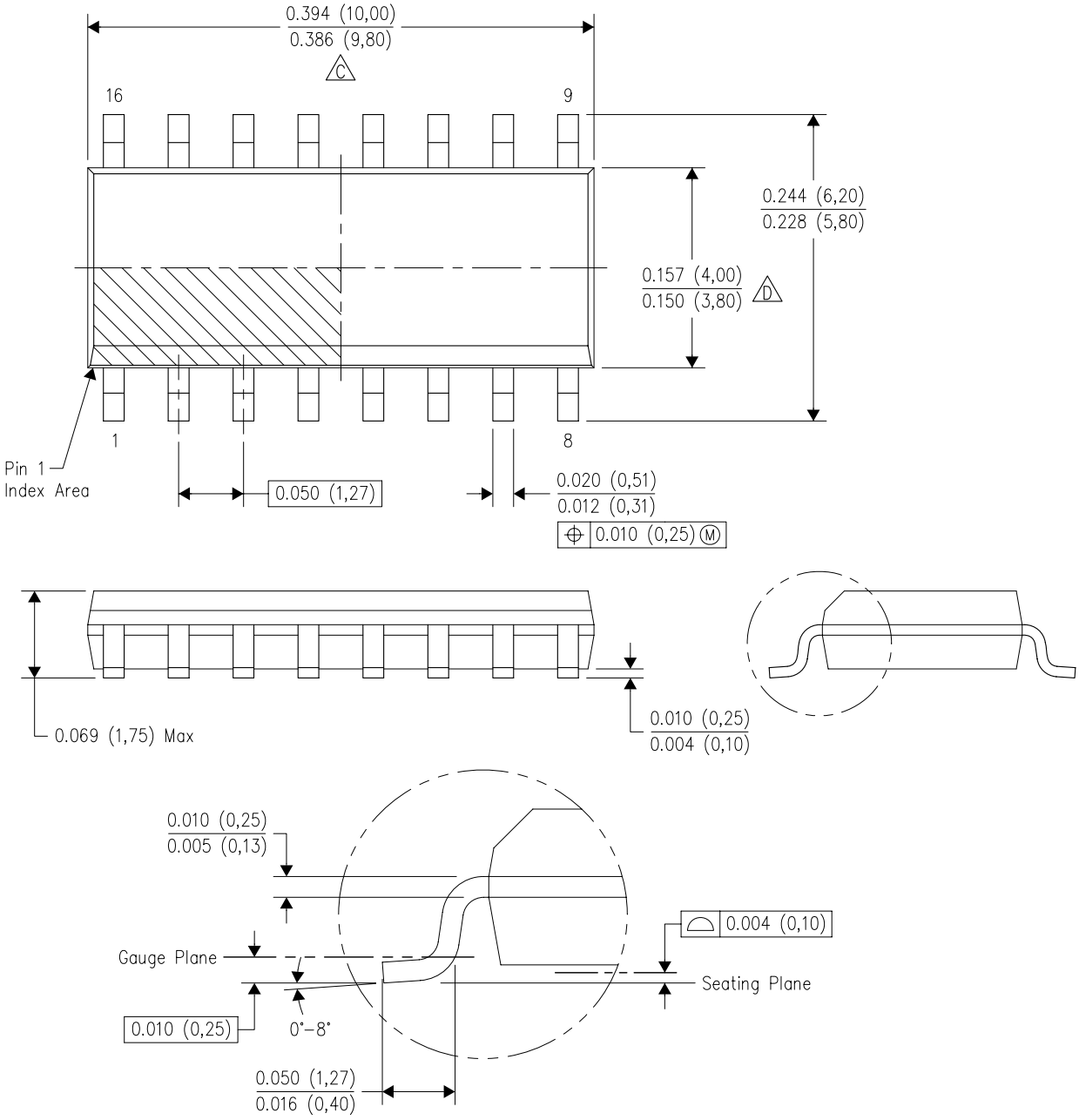
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

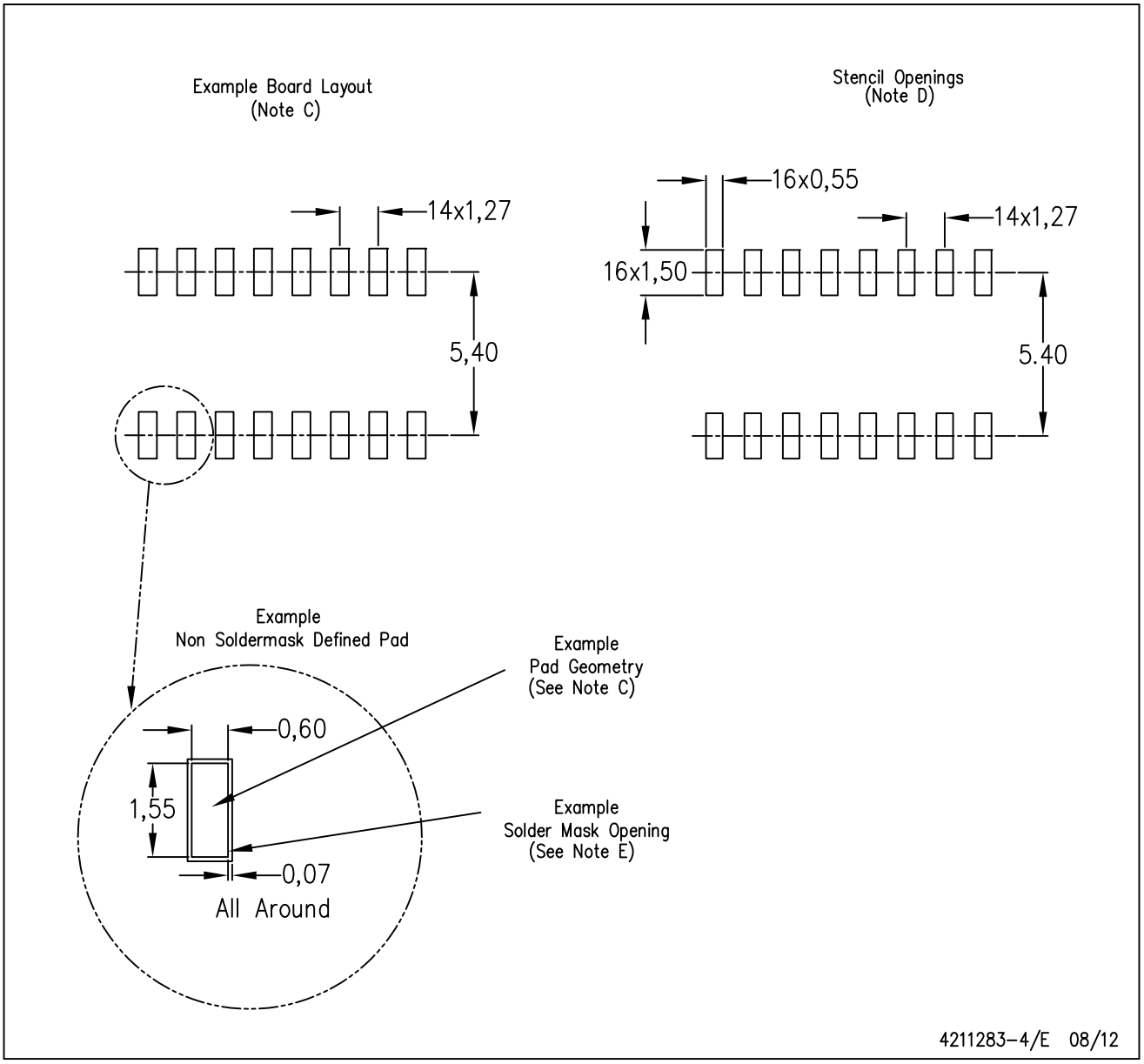
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CLV4052ATPWRG4Q1	TSSOP	PW	16	2000	367.0	367.0	35.0
SN74LV4052AQPWRQ1	TSSOP	PW	16	2000	356.0	356.0	35.0
SN74LV4052ATPWRQ1	TSSOP	PW	16	2000	356.0	356.0	35.0

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



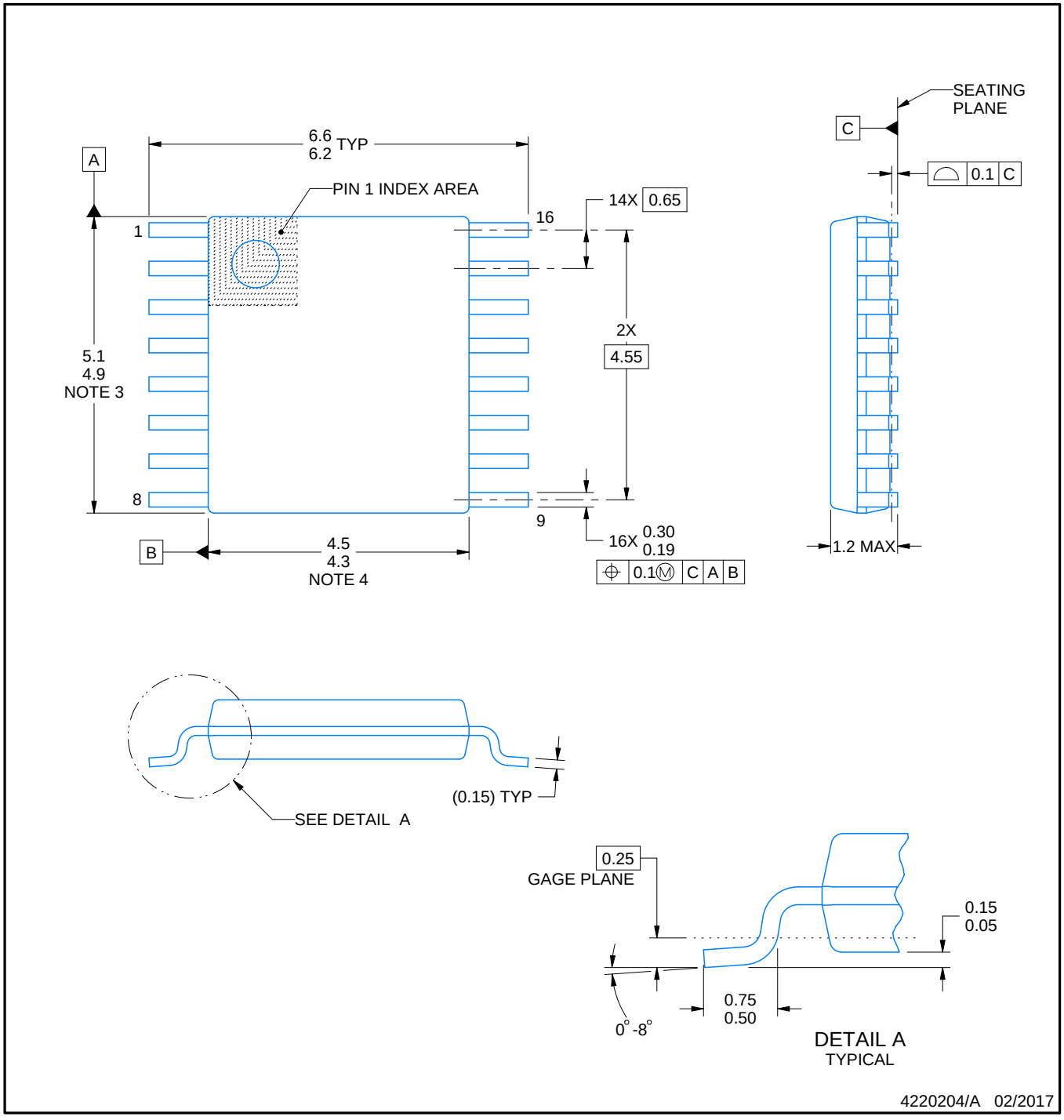
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PACKAGE OUTLINE

PW0016A

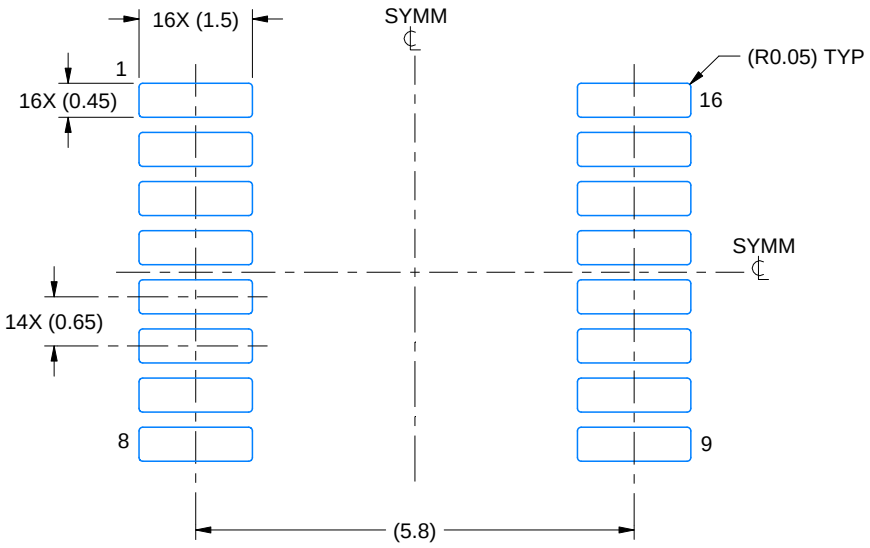
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

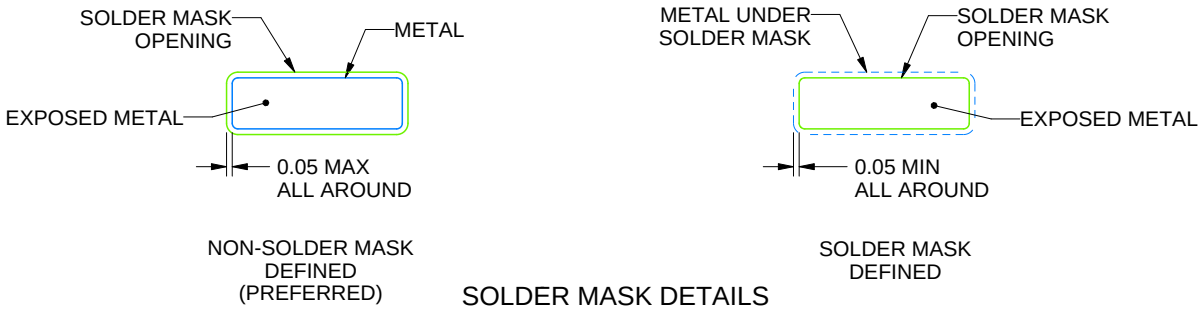


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

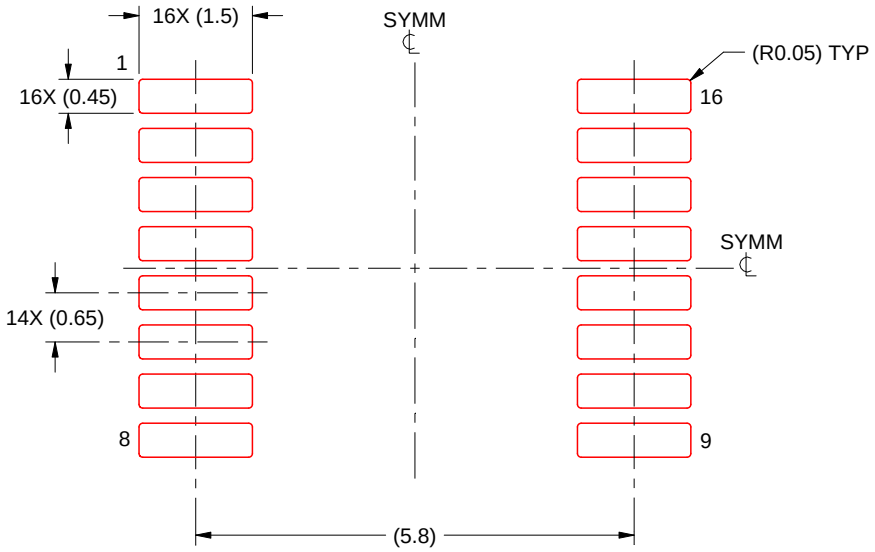


SOLDER MASK DETAILS

4220204/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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